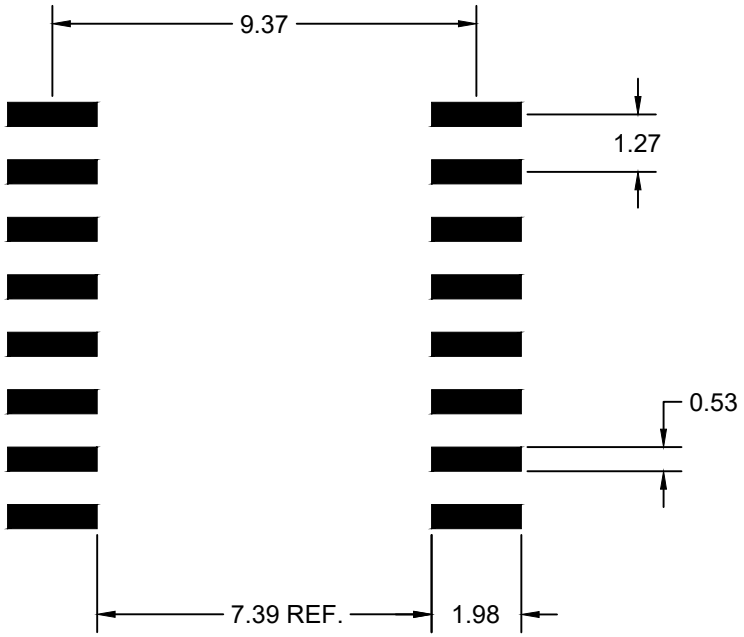
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY

PKG. CODES
[W16-1]
[W16-2]
[W16-3]
[W16-4F]
[W16-6]
[W16-7]
[W16-10]
[W16-11]
[W16-12]
[W16-H2]
[W16M-3]
[W16M-6]
[W16MK-1]
[W16M-8]
[W16M-9]
[W16M-10]
[W16MS-11]
[W16MS-12]
[W16MS-12C]
[W16MS-13]

NOTES:
1. REFERENCE PKG. OUTLINE: 21-0042
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
5. ALL DIMENSIONS IN MM.

–DRAWING NOT TO SCALE–

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.
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TITLE:
PACKAGE LAND PATTERN,
[W16] 0.300" SOIC, 16 LEADS

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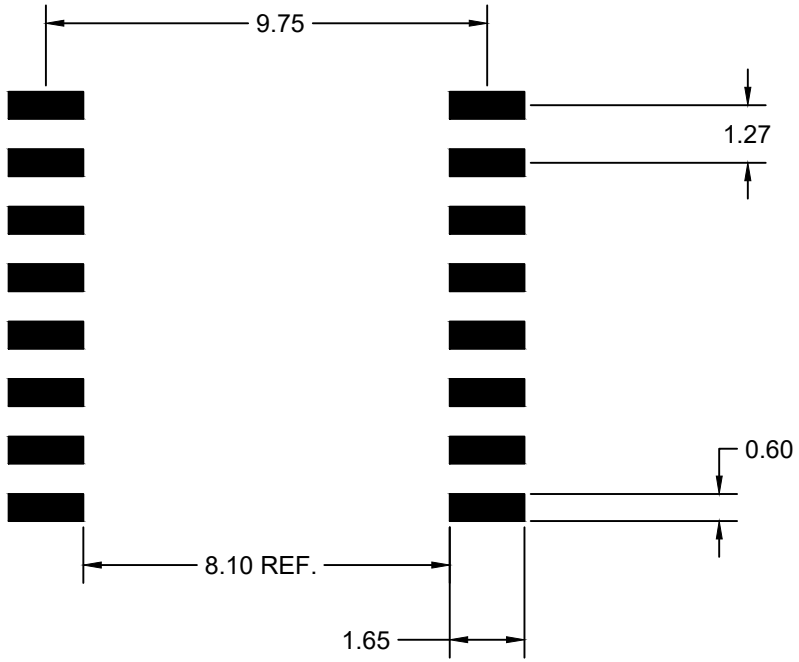
OPTION FOR IMPROVED HV ISOLATION

(CLEARANCE/CREEPAGE OF 8.1MM)



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